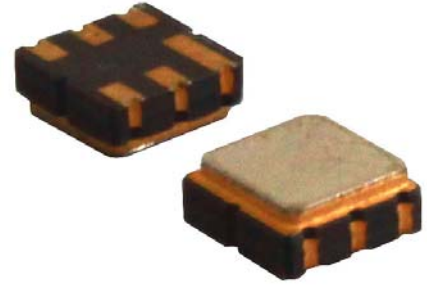


**Application**

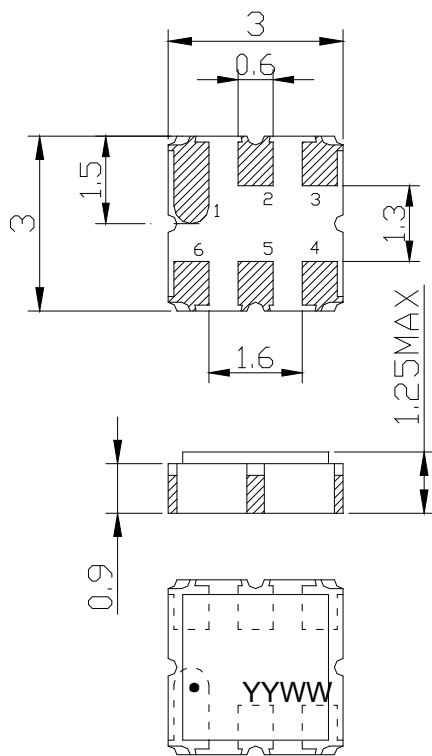
- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 2.0 MHz



**Features**

- Ceramic Package for **Surface Mounted Technology (SMT)**
- **RoHS** compatible
- Package size 3.00x3.00x1.25mm<sup>3</sup>
- Package Code DCC6C
- **Electrostatic Sensitive Device(ESD)**

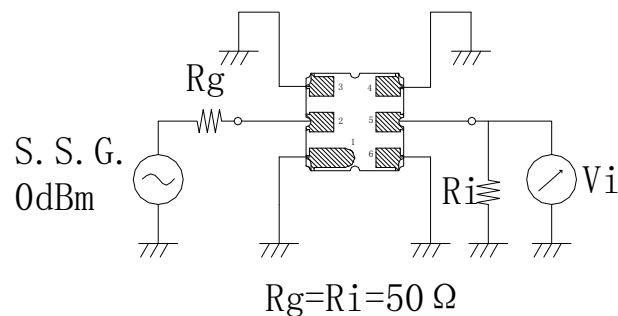
**Package Dimensions (Unit: mm)**



**Pin Configuration**

Pin No.	Description
2	Input
5	Output
1,3,4,6	Case Ground

**Test Circuit (Bottom View)**



**Performance**

**Maximum Rating**

Item		Value	Unit
DC Voltage	V <sub>DC</sub>	3	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-55 ~ +125	°C
RF Power Dissipation	P	10	dBm

**Electronic Characteristics**

Test Temperature: 25°C ± 2°C

Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

Item		Minimum	Typical	Maximum	Unit
Center Frequency	f <sub>c</sub>		869.00		MHz
Insertion Loss(min)	IL		2.3	2.6	dB
Insertion Loss	IL		2.4	3.0	dB
Amplitude Ripple (p-p)	Δα		0.5	1.0	dB
Group Delay Ripple	GDR		5.0	20.0	ns
Absolute Attenuation	α				
	DC - 845.00 MHz	37.0	38.0		dB
	845.00 - 851.00 MHz	35.0	40.0		dB
	851.00 - 856.00 MHz	30.0	35.0		dB
	883.00 - 892.00 MHz	30.0	40.0		dB
	892.00 - 1000.00 MHz	30.0	35.0		dB
Input VSWR			1.4:1	2.0:1	/
Output VSWR			1.4:1	2.0:1	/

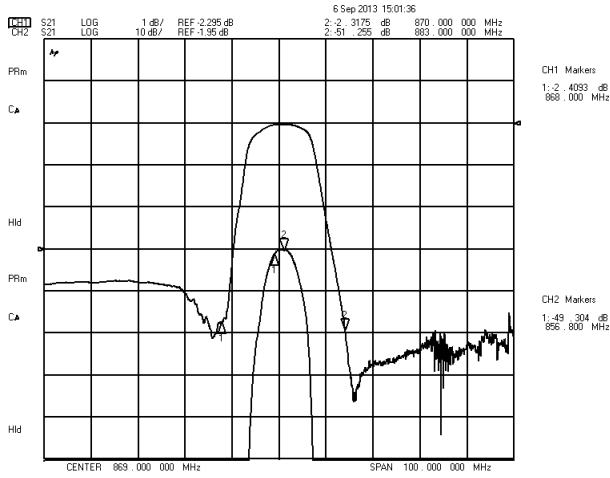
**Frequency Characteristics**

Frequency Response

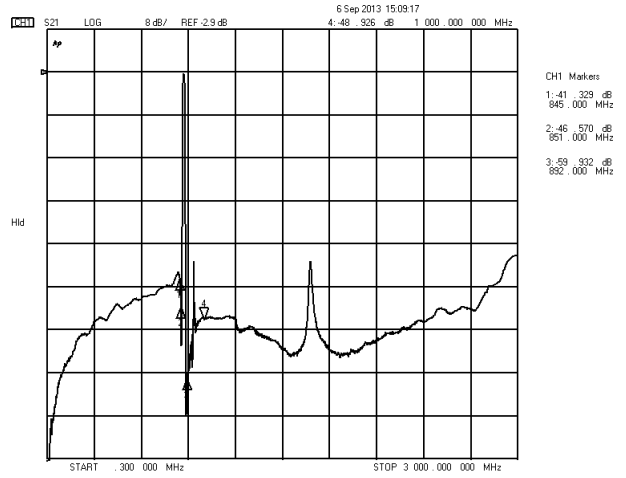
Frequency Response (wideband)

### 869.00MHz SAW Filter

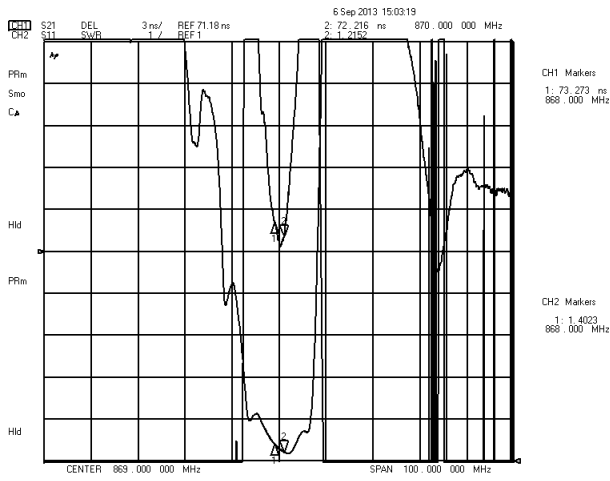
### 2.0MHz Bandwidth



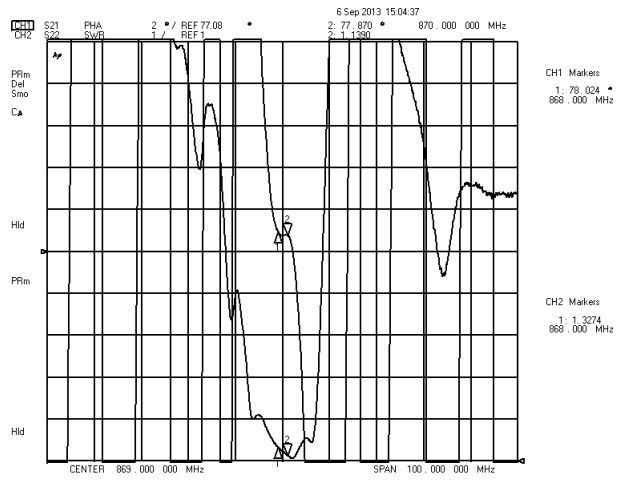
Delay Ripple & S11 VSWR



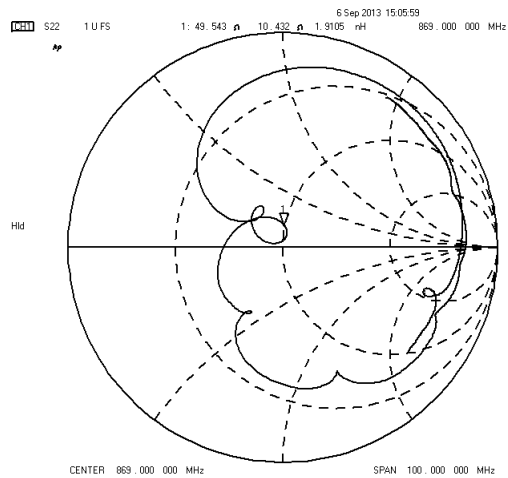
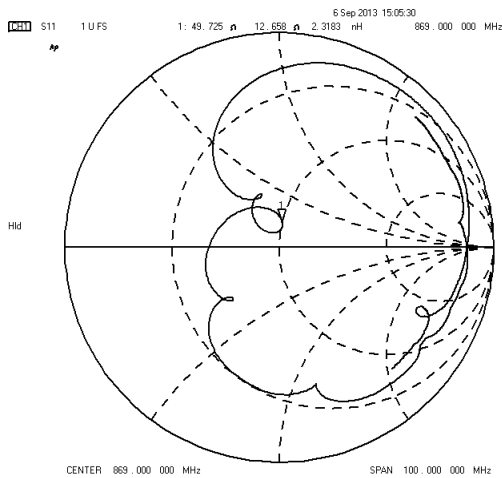
Phase Linearity & S22 VSWR



S11 Smith Chart



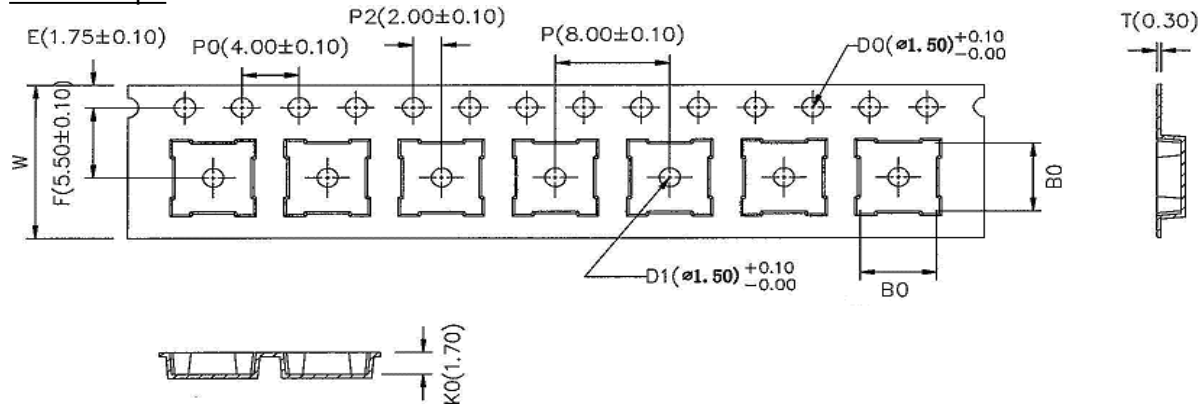
S22 Smith Chart





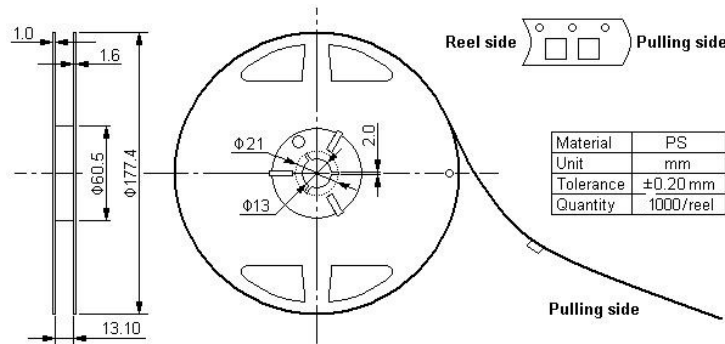
**Packing Information**

Carrier Tape



\* B0: 5.35 for QCC8C; 4.15 for DCC6/QCC8B; 3.35 for DCC6C/QCC8D

Reel Dimensions



Outer Packing

Type	Quantity	Dimension	Description	Weight
Internal box	1000	190×188×42	carton box 2 reel / internal box 5 boxes / external box	0.18
External box	10000	235×205×210		1.80

Unit: mm

Unit: kg

**Notes**

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.